

ABSTRACT OF THE DISCLOSURE

Molding Apparatus

Molding apparatus (200) is provided for simultaneously molding a molding material around a number of separate substrates, each substrate having a semiconductor chip mounted thereon. The apparatus includes a mold holder (113a, 113b, 114, 103) having a first holding section for holding a first mold half (119) and a second holding section for holding a second mold half (120). The first and second holding sections have a common support surface (135), the support surface (135) including a first movable member (104a) in the first holding section and a second movable member (104b) in the second holding section. The first and second movable members (104a, 104b) are movable between a first position in which they protrude out of the support surface (135) and a second position in which the protrusion from the support surface (135) is less than in the first position. A first drive mechanism (100, 110) is coupled to the first movable member (104a) and a second drive mechanism (100, 110) is coupled to the second movable member (104b). The first and second drive mechanisms (100, 110) are adapted to be independently actuated to move the first and second movable members (104a, 104b) between the first and second positions.